

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6221xxxx7R-G
Typical Mass: 1 mg

| Part name | Weight(mg) | Material name | Ratio(ppm) | CAS number |
|--------------|------------|-----------------|------------|------------|
| Silicon chip | 0.148 | Silicon | 148400 | 7440-21-3 |
| | - | Arsenic | <1 | 7440-38-2 |
| Lead pad | 0.239 | Nickel | 239300 | 7440-02-0 |
| | 0.002 | Gold | 1500 | 7440-57-5 |
| Die attach | 0.008 | Epoxy Resin | 8100 | — |
| | 0.005 | Acrylic Resin | 4900 | — |
| Bonding wire | 0.047 | Gold | 47300 | 7440-57-5 |
| | | | | |
| Resin | 0.482 | Silica | 481700 | 60676-86-0 |
| | 0.028 | Epoxy Resin | 27500 | — |
| | 0.025 | Phenol Resin | 24800 | — |
| | 0.017 | Metal hydroxide | 16500 | — |
| | | | | |

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."